IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Compos © Copyright 2005. IPC international and Pan-A	Bannockb	urn, Illinois. A	ll rights reserved untions.	nder both This leve	s docume el parts, th	ent is a declar ne declaration	ration o n encor	of the substar mpasses all l	ower le	thin the manufacturevel materials for wh	er listed it hich the m	em. No anufac	ote: if the cturer has	e item is an ass s engineering r	sembly with lovesponsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Informa	ation															
Company name*			Company unique ID			Unique ID Authority					Response Date*					
nsemi							I					2024-05-11				
Contact Name			Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewar	rds	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Requester	Requester Item Number Mfr Iter		m Number Mfr Item Name				Effective Da	ffective Date		nufacturing Site	Weight*		*	UOM	Unit Type	
		NCP105AMX180TCG 300 mA CM0		300 mA CMOS Lo AD	S Low Dropout Regulator 1V8		2024-05-11			РНМ		1	1.424 mg		mg	Each
Ianufacturing P	Proccess Informatio	n														
Terminal P	l Plating / Grid Array Material Termin		erminal Base A	inal Base Alloy J-STD-020 M		ting	Peak Proces		ss Body Temperature Max Time at Peak		Temperature Number of Reflow C		of Reflow Cycl	les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		au) (no C	CU Alloy 1		1		260		С		30 secon		ds 3	}		
omments							<u> </u>		·							
vel 1 - maximum tir	me at peak temperature	during sol	dering is 10-30) seconds												
or more information	n regarding material co	nposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg	
Die Attach	0.13	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.0416	mg	
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0884	mg	
Lead Frame	0.58	mg	Supplier	Tin (Sn)	7440-31-5		0.0014	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.0013	mg	
			Supplier	Chromium (Cr)	7440-47-3		0.0014	mg	
			Supplier	Copper (Cu)	7440-50-8		0.5758	mg	
Mold Compound-Black	0.6	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.048	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.003	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.012	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.519	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.018	mg	
Plating	0.004	mg	Supplier	Palladium (Pd)	7440-05-3		0.0001	mg	
			В	Nickel (Ni)	7440-02-0		0.0035	mg	
			Supplier	Gold (Au)	7440-57-5		0.0004	mg	
Wire Bond	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg	
			Supplier	Copper (Cu)	7440-50-8		0.0198	mg	